

CAN Bus, ISO11898-2/5, CAN, 4.5 V, 5.5 V, NSOIC

Manufacturers	<u>Microchip Technology, Inc</u>
Package/Case	SOIC-8
Product Type	Interface ICs
RoHS	Rohs
Lifecycle	



Images are for reference only

Please submit RFQ for MCP2562T-E/SN or [Email to us: sales@ovaga.com](mailto:sales@ovaga.com) We will contact you in 12 hours.

[RFQ](#)

## General Description

The MCP2561/2 is Microchip Technology Inc. second generation high-speed CAN transceiver. It serves as an interface between a CAN protocol controller and the physical two-wire CAN bus. The device meets the automotive requirements for high-speed (1 Mb/s), low quiescent current, electromagnetic compatibility (EMC) and electrostatic discharge (ESD). The device family members are: • MCP2561 with SPLIT pin • MCP2562 with VIO pin

## Features

Supports 1 Mb/s operation

Implements ISO-11898-5 standard physical layer requirements

AEC-Q100 Grade 0

Very low standby current (Typ: 5 $\mu$ A)

VIO supply pin (MCP2562) to interface directly to CAN controllers and microcontrollers with 1.8V to 5V I/O

SPLIT output pin (MCP2561) to stabilize common mode in biased split termination schemes

CAN bus pins are disconnected when device is unpowered. An unpowered node or brown-out event will not load the CAN bus

Detection of ground fault; Permanent dominant detection on TXD, Permanent dominant detection on bus

Power-on Reset and voltage brown-out protection on VDD and VIO pin

Protection against damage due to short-circuit conditions (positive or negative battery voltage)

Protection against high-voltage transients in automotive environments

Automatic Thermal Shutdown protection

Suitable for 12V and 24V systems

Up to 112 nodes can be connected

High-noise immunity due to differential bus implementation

High ESD protection on CANH and CANL, IEC61000-4-2 > 8kV

Available in PDIP-8L, SOIC-8L and 3x3 DFN-8L.

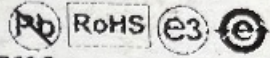
Temperature ranges; Extended (E): -40°C to +125°C, High (H): -40°C to +150°C

(1P) CATALOG P/N: MCP2562T-E/SN

AIB10



(1T) LOT NO.: 181300888000MTAI



MSL: 1/260C  
PKG: SOIC  
LEAD: 8

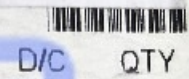
(Q) QTY

2575

(P) CUST. P/N: -



MPC: V7BB2YC2XB00



D/C	QTY
1725	3300
-	-
-	-



SEAL DATE : -  
WAFER QTY: -  
WAFER REV: -  
RECERT D/C: -  
WAFER LOT: -



ID#:( ) TRACE CODE: 1725HKB



MADE IN THAILAND





## Related Products



### [MCP23008T-E/SO](#)

Microchip Technology, Inc  
SOIC-18



### [MCP2551-I/P](#)

Microchip Technology, Inc  
PDIP-8



### [MCP25625T-E/ML](#)

Microchip Technology, Inc  
QFN-28



### [MCP2210-I/SO](#)

Microchip Technology, Inc  
SOP-20



[MCP23008T-E/ML](#)

Microchip Technology, Inc  
QFN-20



[MCP2515T-I/SO](#)

Microchip Technology, Inc  
SOIC-18



[MCP2515T-I/ST](#)

Microchip Technology, Inc  
TSSOP-20



[MCP2562FDT-H/SN](#)

Microchip Technology, Inc  
SOIC-8